



PMEG6010ETR-Q

High temperature 60 V, 1 A low VF Schottky barrier rectifier

22 December 2022

Product data sheet

1. General description

Planar Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD123W small and flat lead Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- Average forward current: $I_{F(AV)} \leq 1$ A
- Reverse voltage: $V_R \leq 60$ V
- Extremely low leakage current
- Low forward voltage
- High power capability due to clip-bonding technology
- Small and flat lead SMD plastic package
- High temperature $T_j \leq 175$ °C
- Qualified according to AEC-Q101 and recommended for use in automotive applications

3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- Reverse polarity protection

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I_F	forward current	$T_{sp} = 165$ °C	-	-	1.4	A
$I_{F(AV)}$	average forward current	$\delta = 0.5$; $f = 20$ kHz; square wave; $T_{amb} \leq 140$ °C	-	-	1	A
		$\delta = 0.5$; $f = 20$ kHz; square wave; $T_{sp} \leq 170$ °C	-	-	1	A
V_R	reverse voltage	$T_j = 25$ °C	-	-	60	V
V_F	forward voltage	$I_F = 1$ A; $T_j = 25$ °C	-	460	530	mV
I_R	reverse current	$V_R = 60$ V; $t_p \leq 300$ μ s; $\delta \leq 0.02$; $T_j = 25$ °C; pulsed	-	30	60	μ A
t_{rr}	reverse recovery time	$I_F = 0.5$ A; $I_R = 0.5$ A; $I_{R(meas)} = 0.1$ A; $T_j = 25$ °C	-	4.4	-	ns

[1] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode[1]	 CFP3 (SOD123W)	 sym001
2	A	anode		

[1] The marking bar indicates the cathode.

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG6010ETR-Q	CFP3	plastic, surface mounted package; 2 terminals; 2.6 mm x 1.7 mm x 1 mm body	SOD123W

7. Marking

Table 4. Marking codes

Type number	Marking code
PMEG6010ETR-Q	EK

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_R	reverse voltage	$T_j = 25\text{ }^{\circ}\text{C}$		-	60	V
I_F	forward current	$T_{sp} = 165\text{ }^{\circ}\text{C}$		-	1.4	A
$I_{F(AV)}$	average forward current	$\delta = 0.5$; $f = 20\text{ kHz}$; square wave; $T_{amb} \leq 140\text{ }^{\circ}\text{C}$	[1]	-	1	A
		$\delta = 0.5$; $f = 20\text{ kHz}$; square wave; $T_{sp} \leq 170\text{ }^{\circ}\text{C}$		-	1	A
I_{FSM}	non-repetitive peak forward current	$t_p = 8.3\text{ ms}$; half-sine wave; $T_{j(init)} = 25\text{ }^{\circ}\text{C}$		-	50	A
P_{tot}	total power dissipation	$T_{amb} \leq 25\text{ }^{\circ}\text{C}$	[2]	-	680	mW
			[3]	-	1.15	W
			[1]	-	2.14	W
T_j	junction temperature			-	175	$^{\circ}\text{C}$
T_{amb}	ambient temperature			-55	175	$^{\circ}\text{C}$
T_{stg}	storage temperature			-65	175	$^{\circ}\text{C}$

[1] Device mounted on a ceramic PCB, Al_2O_3 , standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2 .

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] [2]	-	-	220	K/W
			[1] [3]	-	-	130	K/W
			[1] [4]	-	-	70	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[5]	-	-	18	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².
- [4] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.
- [5] Soldering point of cathode tab.

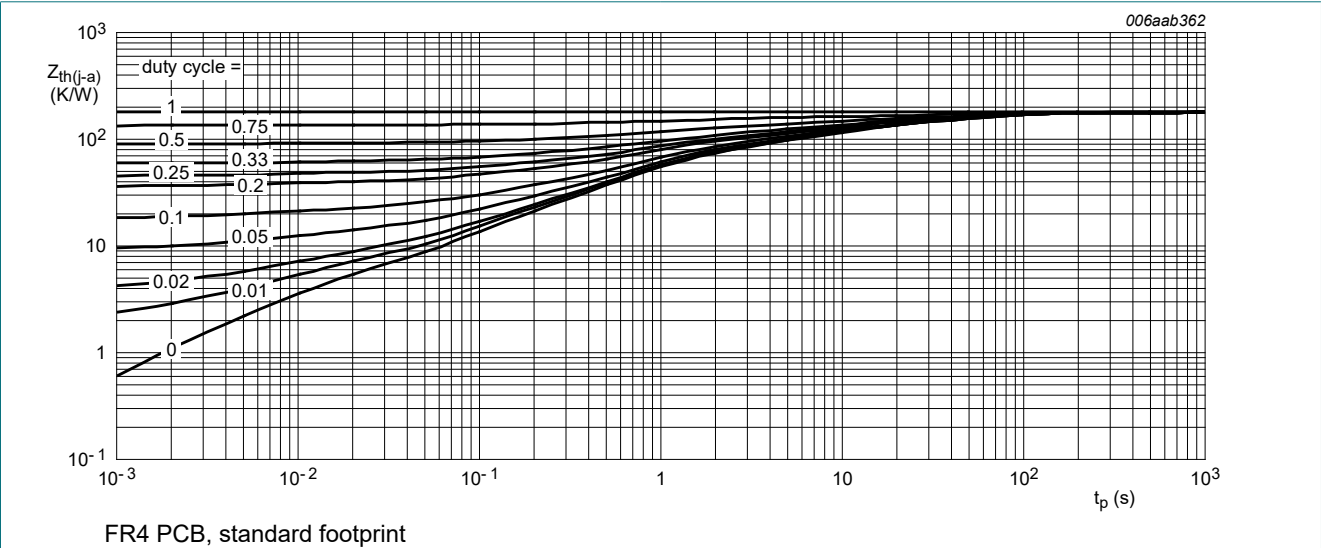


Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

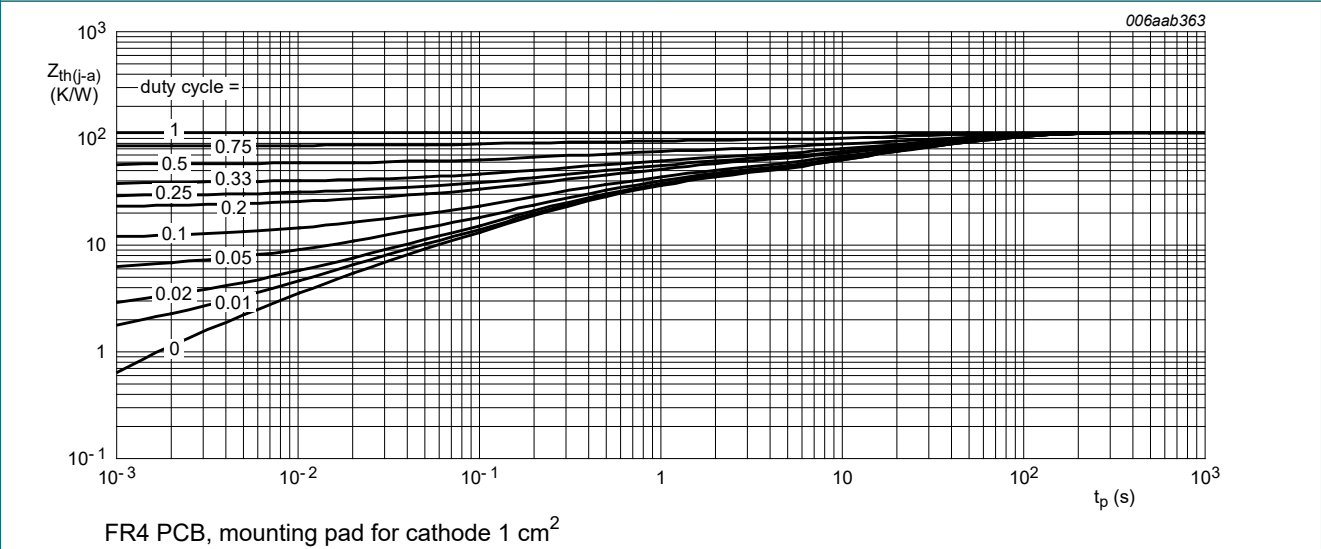
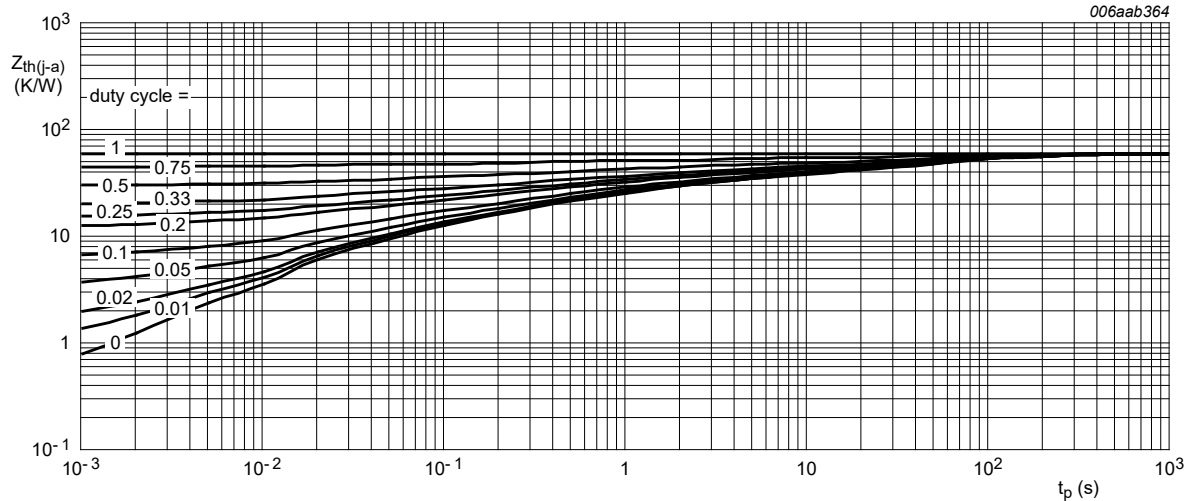


Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



Ceramic PCB, Al₂O₃, standard footprint

Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_F	forward voltage	$I_F = 0.1 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$	-	320	370	mV
		$I_F = 0.7 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$	-	430	490	mV
		$I_F = 1 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$	-	460	530	mV
		$I_F = 1 \text{ A}; T_j = -40 \text{ }^\circ\text{C}$	-	510	590	mV
		$I_F = 1 \text{ A}; T_j = 125 \text{ }^\circ\text{C}$	-	400	480	mV
		$I_F = 1 \text{ A}; T_j = 150 \text{ }^\circ\text{C}$	-	380	460	mV
		$I_F = 1 \text{ A}; T_j = 175 \text{ }^\circ\text{C}$	-	365	450	mV
I_R	reverse current	$V_R = 5 \text{ V}; t_p \leq 300 \text{ } \mu\text{s}; \delta \leq 0.02; T_j = 25 \text{ }^\circ\text{C}; \text{pulsed}$	-	1.2	-	μA
		$V_R = 10 \text{ V}; t_p \leq 300 \text{ } \mu\text{s}; \delta \leq 0.02; T_j = 25 \text{ }^\circ\text{C}; \text{pulsed}$	-	1.7	-	μA
		$V_R = 60 \text{ V}; t_p \leq 300 \text{ } \mu\text{s}; \delta \leq 0.02; T_j = 25 \text{ }^\circ\text{C}; \text{pulsed}$	-	30	60	μA
		$V_R = 60 \text{ V}; t_p \leq 300 \text{ } \mu\text{s}; \delta \leq 0.02; T_j = -40 \text{ }^\circ\text{C}; \text{pulsed}$	-	0.6	10	μA
		$V_R = 60 \text{ V}; t_p \leq 300 \text{ } \mu\text{s}; \delta \leq 0.02; T_j = 125 \text{ }^\circ\text{C}; \text{pulsed}$	-	14	50	mA
C_d	diode capacitance	$V_R = 1 \text{ V}; f = 1 \text{ MHz}; T_j = 25 \text{ }^\circ\text{C}$	-	120	-	pF
		$V_R = 10 \text{ V}; f = 1 \text{ MHz}; T_j = 25 \text{ }^\circ\text{C}$	-	40	-	pF
t_{rr}	reverse recovery time	$I_F = 0.5 \text{ A}; I_R = 0.5 \text{ A}; I_{R(\text{meas})} = 0.1 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$	-	4.4	-	ns
V_{FRM}	peak forward recovery voltage	$I_F = 1 \text{ A}; dI_F/dt = 40 \text{ A}/\mu\text{s}; T_j = 25 \text{ }^\circ\text{C}$	-	500	-	mV

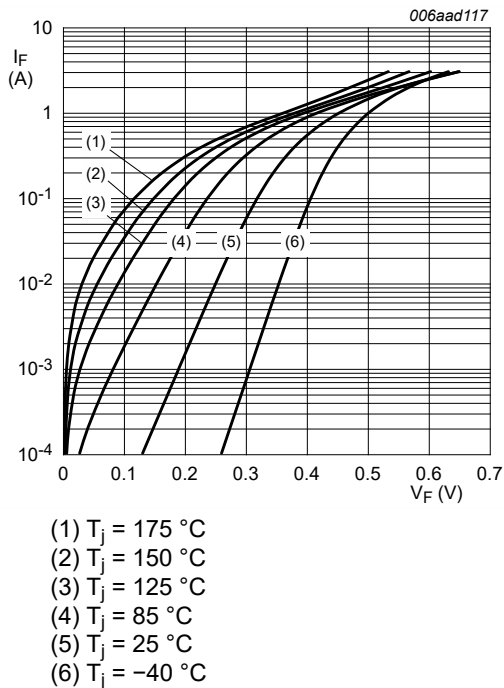


Fig. 4. Forward current as a function of forward voltage; typical values

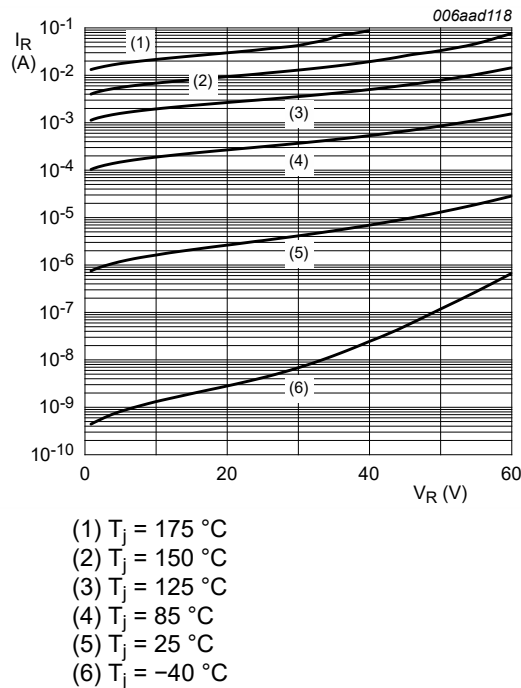


Fig. 5. Reverse current as a function of reverse voltage; typical values

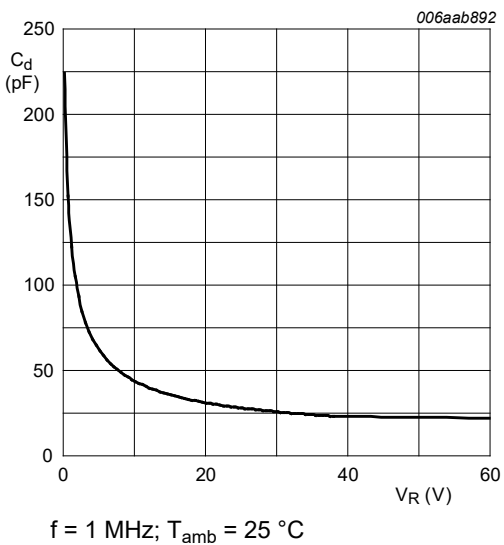


Fig. 6. Diode capacitance as a function of reverse voltage; typical values

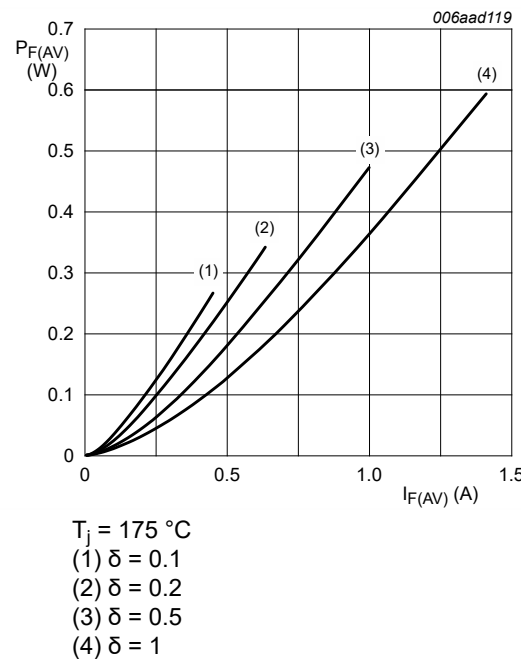


Fig. 7. Average forward power dissipation as a function of average forward current; typical values

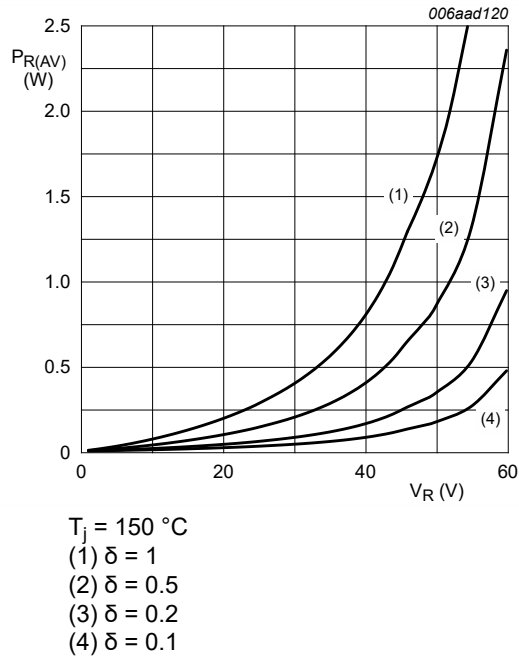


Fig. 8. Average reverse power dissipation as a function of reverse voltage; typical values

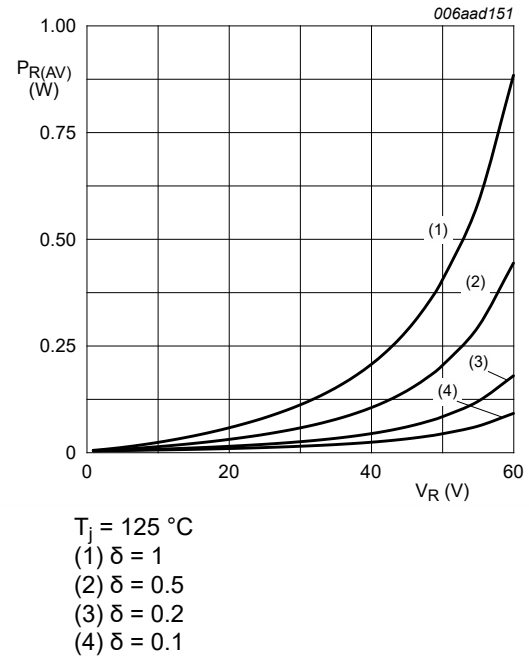


Fig. 9. Average reverse power dissipation as a function of reverse voltage; typical values

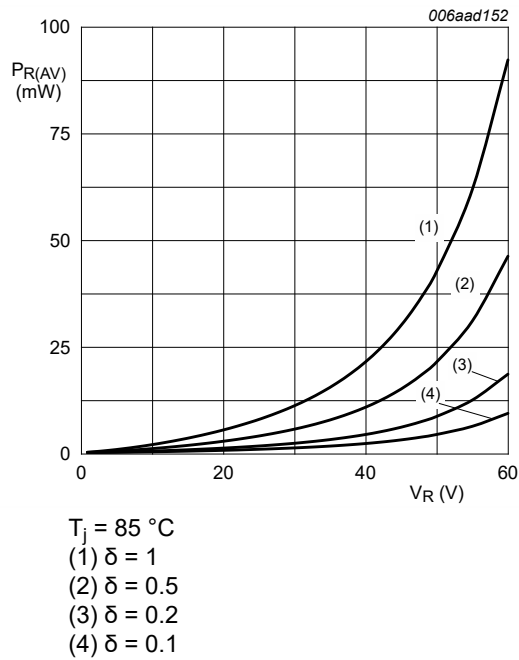


Fig. 10. Average reverse power dissipation as a function of reverse voltage; typical values

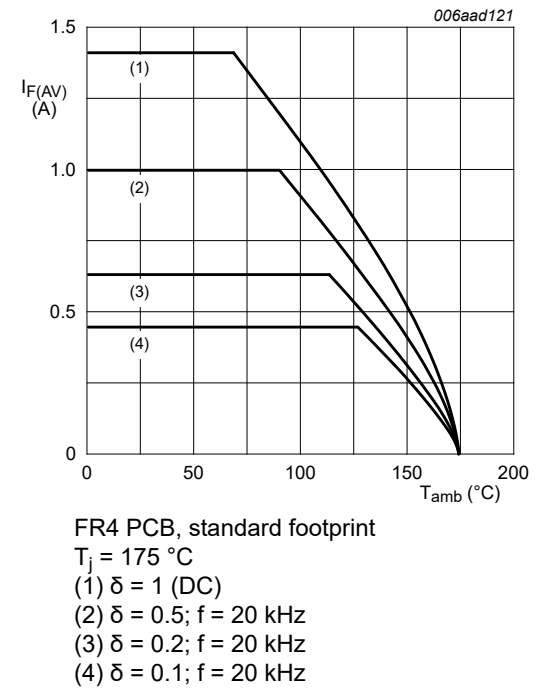
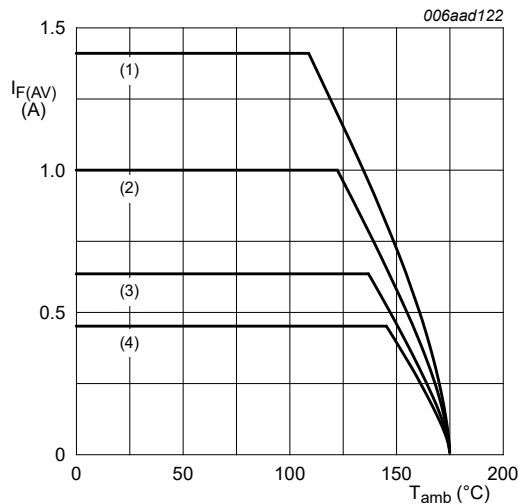
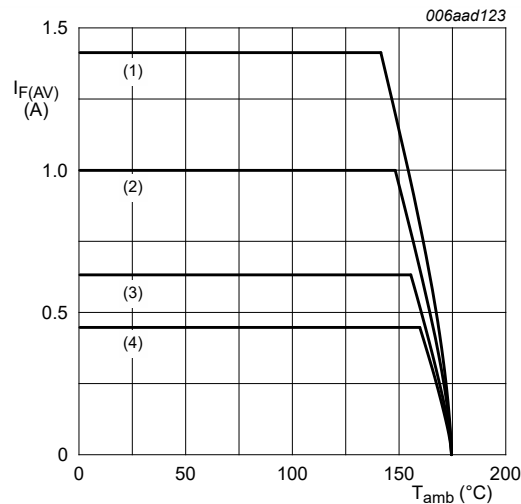


Fig. 11. Average forward current as a function of ambient temperature; typical values



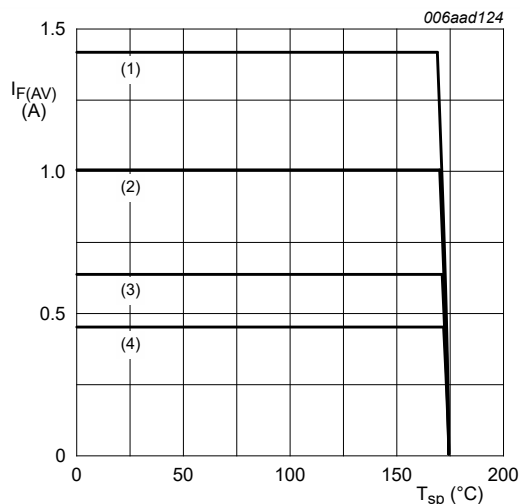
FR4 PCB, mounting pad for cathode 1 cm²
 $T_j = 175$ °C
(1) $\delta = 1$ (DC)
(2) $\delta = 0.5$; $f = 20$ kHz
(3) $\delta = 0.2$; $f = 20$ kHz
(4) $\delta = 0.1$; $f = 20$ kHz

Fig. 12. Average forward current as a function of ambient temperature; typical values



Ceramic PCB, Al₂O₃, standard footprint
 $T_j = 175$ °C
(1) $\delta = 1$ (DC)
(2) $\delta = 0.5$; $f = 20$ kHz
(3) $\delta = 0.2$; $f = 20$ kHz
(4) $\delta = 0.1$; $f = 20$ kHz

Fig. 13. Average forward current as a function of ambient temperature; typical values



$T_j = 175$ °C
(1) $\delta = 1$ (DC)
(2) $\delta = 0.5$; $f = 20$ kHz
(3) $\delta = 0.2$; $f = 20$ kHz
(4) $\delta = 0.1$; $f = 20$ kHz

Fig. 14. Average forward current as a function of solder point temperature; typical values

11. Test information

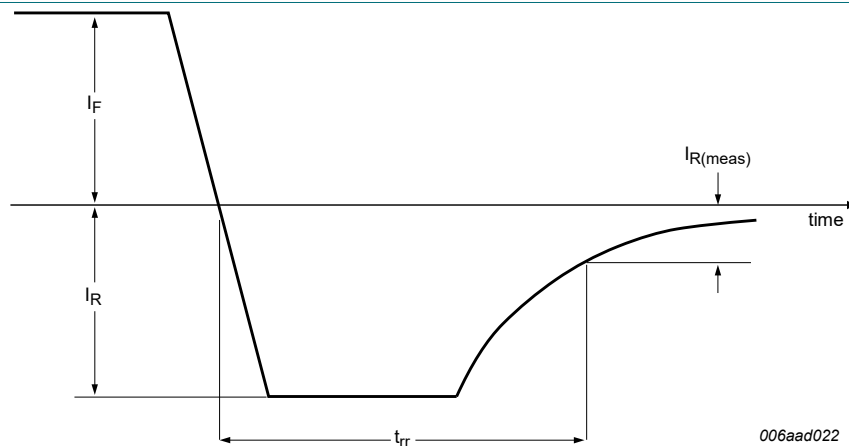


Fig. 15. Reverse recovery definition

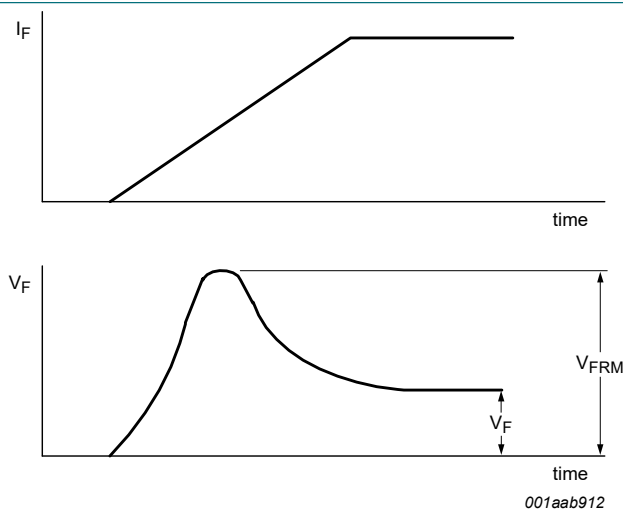


Fig. 16. Forward recovery definition

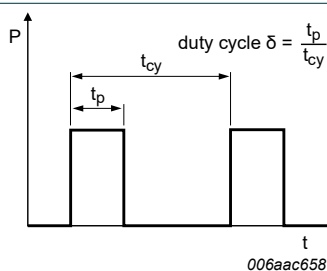


Fig. 17. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations:

$$I_{F(AV)} = I_M \times \delta \text{ with } I_M \text{ defined as peak current,}$$

$$I_{RMS} = I_{F(AV)} \text{ at DC,}$$

$$I_{RMS} = I_M \times \sqrt{\delta} \text{ with } I_{RMS} \text{ defined as RMS current.}$$

Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

12. Package outline

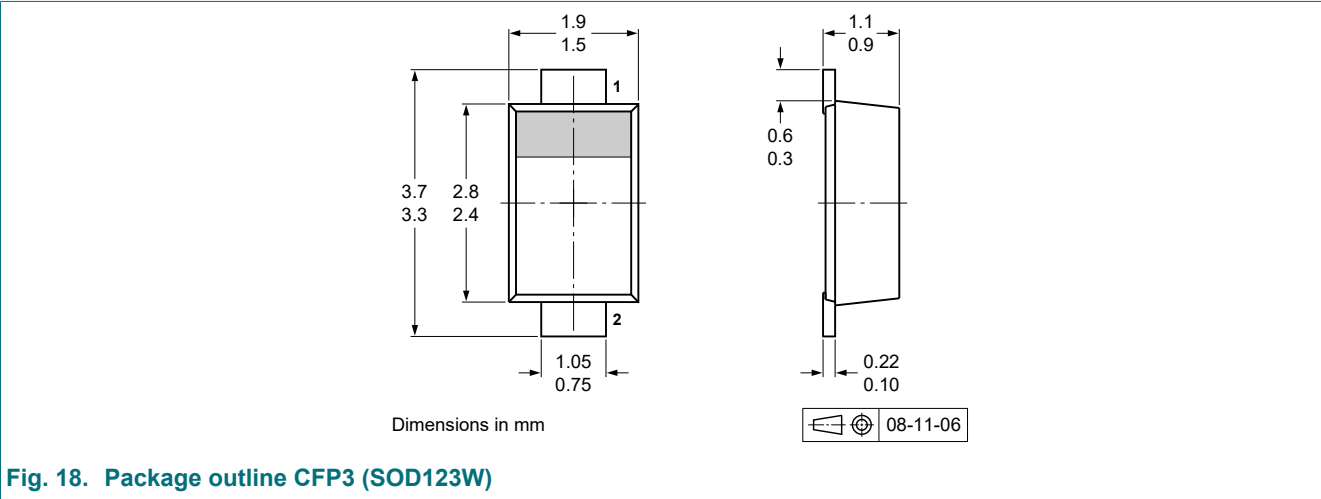
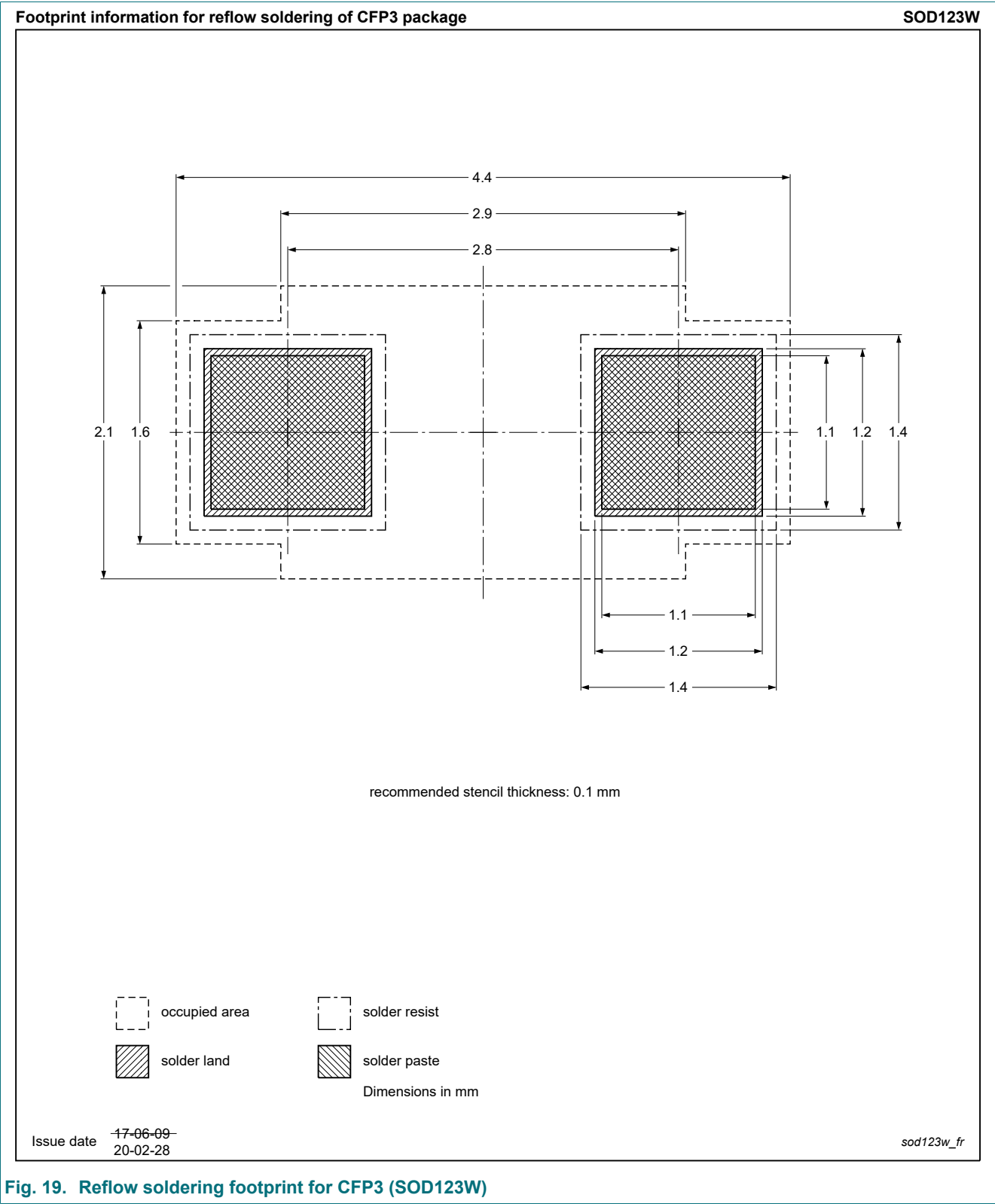


Fig. 18. Package outline CFP3 (SOD123W)

13. Soldering



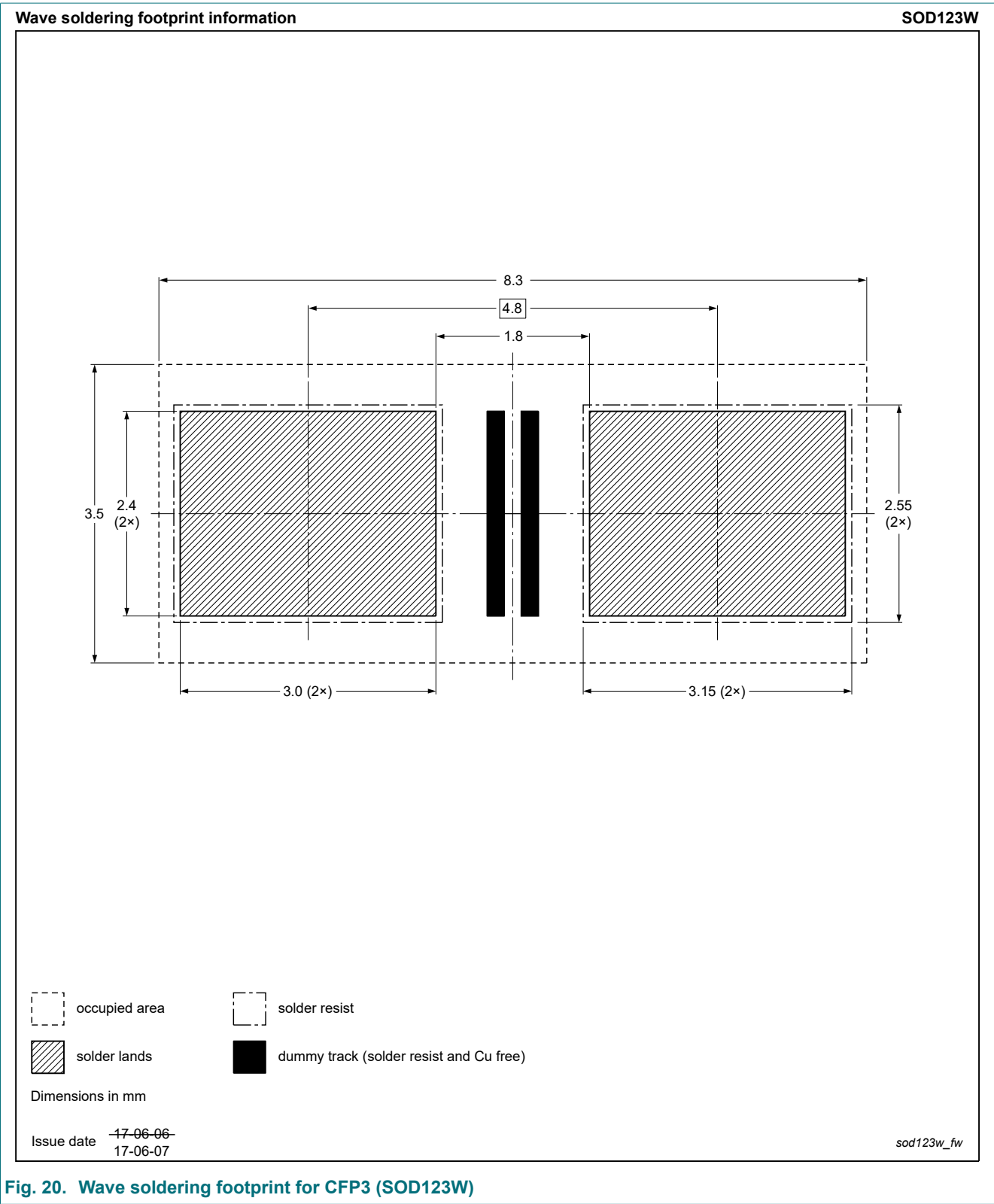


Fig. 20. Wave soldering footprint for CFP3 (SOD123W)

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG6010ETR-Q v.2	20221222	Product data sheet	-	PMEG6010ETR-Q v.1
Modifications:	Limiting values: Measurement conditions for I_{FSM} changed from square wave to half-sine wave.			
PMEG6010ETR-Q v.1	20210719	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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Contents

1. General description.....	1
2. Features and benefits.....	1
3. Applications.....	1
4. Quick reference data.....	1
5. Pinning information.....	2
6. Ordering information.....	2
7. Marking.....	2
8. Limiting values.....	2
9. Thermal characteristics.....	3
10. Characteristics.....	4
11. Test information.....	8
12. Package outline.....	9
13. Soldering.....	10
14. Revision history.....	12
15. Legal information.....	13

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